

Abstract

The present invention relates to a micro optical communication device package. The package of the invention comprises a Micro-Electro-Mechanical System (MEMS) chip for 5 executing an optical communication function. The MEMS chip is mounted on a base. An upper housing having an opened bottom is placed on the base to form an internal space together with the base. The upper housing is sealed with the base to hermetically seal the MEMS chip within the internal space. The MEMS chip is 10 connected an optical fiber, which is extended through the upper housing to form a light path. A boot is fit around the optical fiber and fixed to the upper housing to seal a portion of the upper housing for allowing passage of the optical fiber.